



PTO-1449 (MODIFIED)  LIST OF PATENTS AND PUBLICATIONS FOR APPLICANTS INFORMATION DISCLOSURE STATEMENT	ATTORNEY DOCKET NO.  SP01-300	SERIAL NO.  10/035,358
	APPLICANT: Filhaber et al.	
	FILING DATE October 26, 2001	GROUP: 2812

REFERENCE DESIGNATION				U.S. PATENT DOCUMENTS			
Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Sub-Class	Translation Yes No
	AL						
	AM						
	AN						
	AO						
	AP						
	AQ						

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)		
mc	AR	Andreas Plohl et al., Wafer Direct Bonding: Tailoring Adhesion Between Brittle Materials, Materials Science and Engineering, R25 (1999) pp. 1-88.
	AS	
	AT	
	AU	
	AV	
	AW	

EXAMINER: Michelle R. Connelly-Cushwa DATE CONSIDERED: 2/11/04  
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609: draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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LIST OF PATENTS AND  
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SP01-300

10/035358

APPLICANT :Filhaber, John F., et al.

FILING DATE 10/26/2001

GROUP: 2874

## REFERENCE DESIGNATION

## U.S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
mc	AA	4,186,999	2/5/80	Harwood et al	350	96.21	10/25/77
mc	AB	4,407,667	10/4/83	Le Noane et al	65	3.11	7/20/81
mc	AC	4,530,452	7/23/85	Balyasny et al	225	96	8/29/84
mc	AD	4,626,068	12/2/86	Caldwell	350	96.34	7/29/82
mc	AE	5,183,710	2/2/93	Gerbino	428	405	4/23/91
mc	AF	5,451,547	9/19/95	Himi et al	437	225	8/25/92
mc	AG	5,452,122	9/19/95	Tsuneda et al	359	281	8/5/91
mc	AH	5,785,874	7/28/98	Eda	216	24	8/4/95
mc	AI	5,852,622	12/22/98	Meissner et al	372	39	9/11/96
mc	AJ	5,989,372	11/23/99	Momoda et al	156	89.11	5/7/98
mc	AK	6,030,883	2/29/00	Nishimoto et al	438	455	5/20/97
mc	AL	6,048,103	4/11/00	Furukata et al	385	73	6/3/99
mc	AM	6,098,429	8/8/00	Mazabraud et al	65	392	2/4/99
mc	AN	6,178,779	1/30/01	Drouart et al	65	391	3/30/99
mc	AO	6,249,619	6/19/01	Bergmann	385	11	9/17/98
mc	AP	6,275,336	8/14/01	Yoshikawa et al	359	484	7/30/97
mc	AQ	6,359,733	3/19/02	Iwatsuka et al	359	500	8/14/00
mc	AR	6,429,144	8/6/02	Vines et al	438	745	12/28/99
mc	AS	2003/0079823	5/1/03	Sabia	156	99	9/25/02
mc	AT	2003/0079503	5/1/03	Cook et al	65	407	10/26/01

## FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Sub-Class	Translation	
							Yes	No
mc	AU	DE2130905	1/11/73	Germany	01	19/56		X
mc	AV	DE19731075	1/21/99	Germany	03	29/00		X
mc	AW	WO01/98225	12/27/01	PCT	03	27/06	X	
mc	AX	WO01/73831	10/4/01	PCT	01	21/304		X
mc	AY	WO00/17698	3/30/00	PCT	02	1/09	X	
mc	AZ	EP1057793	3/13/02	Europe	03	37/027	X	

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*Michelle R. Connelly-Cushwa**2/11/04*

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OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

MC	BA	Arthur Landrock. "Adhesives Technology Handbook." 1985, p. 117-118.
MC	BB	Yoshikawa Hiroki; Japanese abstract of 2002321947; 11/8/02 "Optical Device and Method for Producing the Same"
MC	BC	Furukata; Japanese Abstract of Publication No. 08146351; 6/7/96; "Element for Optical Isolator and its Production"
MC	BD	Ohashi et al; Japanese Abstract of Publication No. 03-115178; 5/16/91; "Method for Joining Aluminum or Aluminum Ceramics by Diffusion".
MC	BE	Onishi et al; "A Novel Temperature Compensation Method for SAW Devices Using Direct Bonding Techniques"; IEEE Ultrasonics Symposium; 1997; pages 227-230.
	AV	
	AW	

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*2/11/04*

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